



Reliability Laboratory

## TEST REPORT

Report No.: HC80281/2007  
Page: 1 of 4  
Date: August 31, 2007

TEMWELL CORPORATION  
8F-1, NO. 51, SEC. 1, MIN SHENG E. RD.,  
TAIPEI, TAIWAN

The following merchandise was submitted and identified by the vendor as:

Product Description: TEMWELL BRAND Helical Filter  
Style/Item No.: 7H/ No.1~ No.5  
Manufacturer/Vendor: TEMWELL CORPORATION  
Quantity: Total 5 pieces  
Testing Period: Aug. 28, 2007 to Aug. 29, 2007  
Note: (Client's declaration) The materials used for 7H series are similar.

We have tested the submitted sample(s) as requested and the following results were obtained:

Test Required : (According to client's test specification, please see following sheets in detail.)

1. Resistance to Soldering Heat Test

Test Results: - PLEASE SEE ATTACHED SHEETS -

Terence Hsieh  
Asst. Manager

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## 1. Resistance to Soldering Heat by Solder Dip:

### Test Equipment:

Name	Brand	Model	Serial No.
Solderability Tester	Multicore	MUST II PLUS	9652

### Materials:

Name	Brand	Designation	Chemical Composition
Solder	SENJU	M705E	Sn/3.0Ag/0.5Cu
Flux	Sharemate	SM/NA (Unactivated)	25 wt% of Colophony in 75wt% of 2-propanol

### Lab Environmental Conditions:

Ambient temperature: 25±3°C  
 Relative humidity: 55±20%RH

### Test Method/ Specification:

Test Method: Reference to MIL-STD-202G Method 210F Condition B

Sample Condition: See below item marked “●”,

●	As-received condition
	Specimen shall be cleaned (Immersed in a neutral organic solvent at room temperature and dried in air)

Type of Flux: Unactivated

Solder Composition: Sn/3.0Ag/0.5Cu

Test Temperature: 260±5°C

Immersion Angle: 90°

Immersion/Emersion Rate: 25±6 mm/s

Immersion Depth: Terminations shall be immersed to within 1.27 mm of the component body or to the seating plane (whichever is further from the component body)

Dwell Time: 10±1 seconds

\* Leads should be immersed in the flux for 5 to 10 seconds before soldering.

\* If flux used, all leads shall have all visible flux residues removed by alcohol before examination.

Number of Heat Cycles: 1 time(s)

Test Requirement: Examine the appearance of specimens visually before and after this test.

Note: The component shall be placed on the FR-4 mounting board during test.

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Specimen:




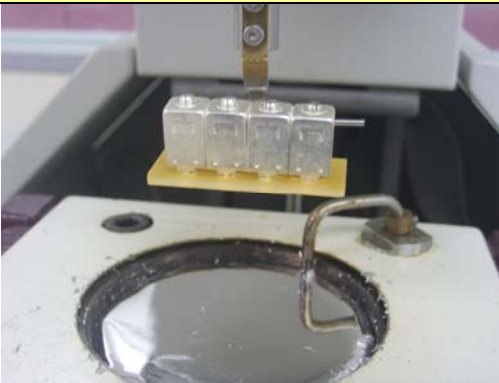

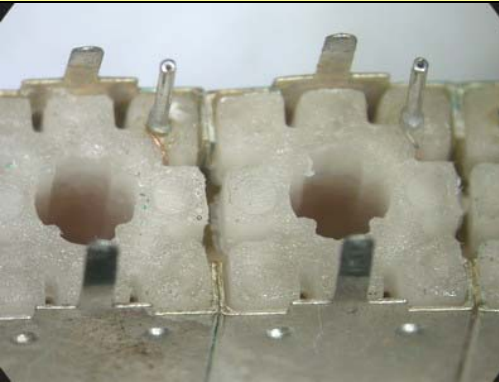
Style/Item No.: 7H/ No.1~ No.5

Quantity: 5 piece(s)

Test Result:

Check Item Style/Item No.	Initial Inspection	Final Inspection
	Any visible defect be found?	Any external defect be found?
<b>7H/ No.1</b>	No	No
<b>7H/ No.2</b>	No	No
<b>7H/ No.3</b>	No	No
<b>7H/ No.4</b>	No	No
<b>7H/ No.5</b>	No	No

Test Photos:

	
<p>1. Appearance of specimen-- (7H)</p>	<p>2. Testing area of specimen</p>
	
<p>3. Resistance to Soldering Heat by Solder Dip</p>	<p>4. Resistance to Soldering Heat by Solder Dip</p>
	
<p>5. Final Inspection-- Resistance to Soldering Heat by Solder Dip</p>	<p>6. Final Inspection-- Resistance to Soldering Heat by Solder Dip</p>

— — — **The End of Test Report** — — —